Unique Soak and Spray Wafer Processing

The WaferStorm™ Platform

WaferStorm: Metal Lifter
- Heated immersion tank
- High-pressure spray chamber
- Lift-off material filtration system
- High-pressure flow monitoring
- Low chemical consumption

WaferStorm: TSV Cleaner and Post Etch Residue Remover
- Heated immersion tank
- High-pressure spray chamber
- Low chemical consumption

WaferStorm: Thick Film Remover
- Heated, recirculating, solvent immersion tank
- High-pressure spray up to 3000 psi
- HPC needle- and HPC fan-spray modes
- Flow rate monitoring system
- Low chemical consumption

WaferStorm: Flux Cleaner
- Complete flux removal

Veeco
Precision Surface Processing
The WaferStorm™ is a solvent-based platform, available in customizable configurations. TSV Cleaner, Metal Lifter, and Thick Film Remover are three examples. All WaferStorm systems are based on Veeco's unique soak-and-spray technology, which provides improved performance at lower cost of ownership than conventional wet-bench-only or spray-only approaches. The process combines equal soak time in the wet buffer tank for each wafer, followed by spray, and then a final step depending on the process being performed. This unique combination minimizes both spray time and chemistry use, and adds a significant level of control during wafer processing. The reduction in spray time results in increased throughput.

The WaferStorm platform is available in multiple configurations, including:

**TSV Cleaner**
- Complete sidewall polymer removal
- Complete photoresist removal

**Metal Lifter**
- Complete metal removal through material filtration station

**Thick Film Remover**
- Patent-pending DFR filtration
- Resist removal

**Flux Cleaner**
- Complete flux removal